



Statement of Materials, Construction

80L MQFP 14x14 -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.21993	Cu	7440-50-8	0.20794	21.19281	94.55
				Fe	7439-89-6	0.00044	0.04483	0.20
				Zn	7440-32-6	0.00220	0.22414	1.00
				Pb	7439-92-1	0.00011	0.01121	0.05
				Ni	7440-02-0	0.00704	0.71726	3.20
				Mn	7439-96-5	0.00022	0.02241	0.10
				Si	7440-21-3	0.00159	0.16250	0.73
				Mg	7439-95-4	0.00038	0.03923	0.18
2	Die	Silicon Chip	0.03881	Si	7440-21-3	0.03881	3.95485	99.50
3	Die Attach Material	Conductive Epoxy	0.02600	Epoxy Resin	Proprietary	0.00390	0.39747	15.00
				Ag	7440-22-4	0.02067	2.05361	79.50
				Aromatic Amine	Proprietary	0.00143	0.14574	5.50
4	Wire	Gold	0.00367	Au	7440-57-5	0.00367	0.37399	99.99
5	Lead Finish	Alloy	0.06080	Pb	7439-92-1	0.00608	0.61977	10.00
				Sn	7440-31-5	0.05472	5.57795	90.00
6	Encapsulation	Epoxy Resin	0.63180	Fused Silica	60676-86-0	0.53324	54.73196	84.40
				Epoxy Cresol Novalac	29690-82-2	0.05433	5.53759	8.60
				Phenol Novalac	9003-35-4	0.03159	3.21953	5.00
				Antimony Trioxide	1309-64-4	0.01264	1.28781	2.00
Total Package weight			0.98101					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%